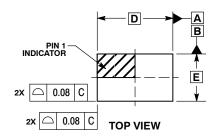
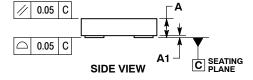
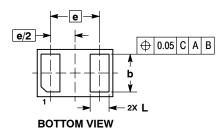


UDFN2 2.0x1.25, 1.3P CASE 517DF **ISSUE A** 

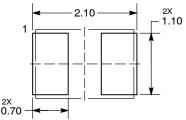
**DATE 06 JUL 2016** 







## **RECOMMENDED SOLDERING FOOTPRINT\***

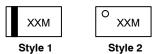


DIMENSIONS: MILLIMETERS

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.45	0.55	
<b>A</b> 1	0.00	0.05	
ь	0.95	1.05	
ם	2.00 BSC		
Е	1.25 BSC		
е	1.30 BSC		
L	0.45	0.55	

## **GENERIC MARKING DIAGRAMS\***



= Specific Device Code XX= Date Code M

STYLE 1: STYLE 2: NO POLARITY CATHODE PIN 1. (POLARITY BAND) ÀNODE

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

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	DESCRIPTION:	UDFN2 2.0X1.25, 1.3P		PAGE 1 OF 1

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.